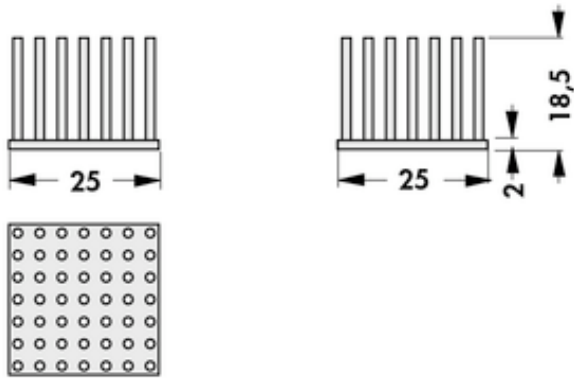
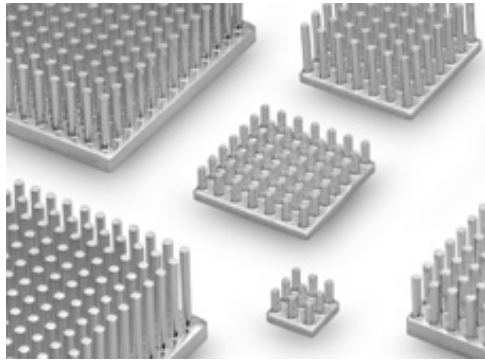


Pin heatsinks / **ICK S 25 x 25 x 18,5**

25 x 25 x 18,5 mm, pin heatsinks quadratic

Parameters of article ICK S 25 x 25 x 18,5

Bauform	Rechteck
R_{th} [K/W]	5.2
dissipation loss [W]	14.4
mounting method	therm. conductive foil / therm. cond. adhesive
socket	universal
suitable for processor type	universal
width [mm]	25
height [mm]	18.5
plate thickness [mm]	2
weight [g]	7
length on stock [mm]	25

Accessories/ related articles

Thermally conductive foil both sides adhesive / **WLFT 404 25 x 25**

Thermally conductive foil both sides adhesive / **WLFT 405 25 x 25**

